

ABSTRACT OF THE DISCLOSURE

The overflow of a brazing material (19) from a die pad (11) is prevented by forming a second plating film (14B) on the surface of the die pad (11). The second plating film (14B) is provided around the surface of the die pad 11 so as to enclose an area where a semiconductor element (13) is mounted. In a step of mounting the semiconductor element (13) on the die pad (11) with the brazing material (19), the brazing material (19) overflows from the first plating film (14A) when the semiconductor element (13) is mounted on the upper part of the molten brazing material. However, the second plating film (14B) functions as a blocking area by which the overflow of the brazing material is prevented. Therefore, a short circuit can be prevented from arising between the die pad (11) and the bonding pad (12) because of the brazing material that has spread.